

6-104074-1 ✓ ACTIVE

AMPMODU | AMPMODU System 50

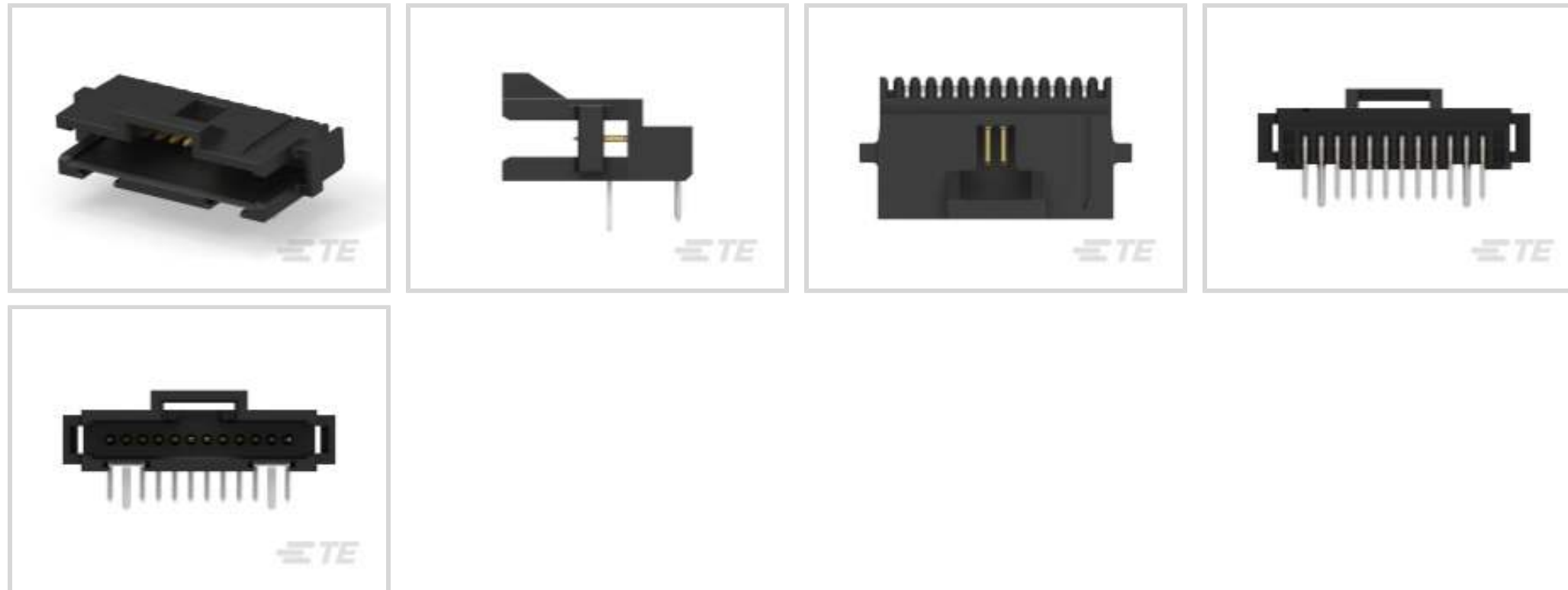
TE Internal #: 6-104074-1

PCB Mount Header, Right Angle, Board-to-Board, 12 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, AMPMODU System 50

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Board-to-Board**

Number of Positions: **12**

Number of Rows: **1**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Right Angle
Number of Positions	12
Number of Rows	1
Board-to-Board Configuration	Perpendicular

Electrical Characteristics

Dielectric Withstanding Voltage (Max)	500 VAC
Insulation Resistance	5000 MΩ



Operating Voltage	30 VAC
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Body Features

PCB Retention Feature Plating Material	Tin over Nickel
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Connector Profile	Standard
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Primary Product Color	Black
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Contact Features

Mating Square Post Dimension	.38 mm[.015 in]
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PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μ m[150 – 250 μ in]
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PCB Contact Termination Area Plating Material Finish	Matte
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Contact Shape & Form	Rectangular
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Contact Underplating Material	Nickel
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PCB Contact Termination Area Plating Material	Tin
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Contact Base Material	Copper Alloy
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Contact Mating Area Plating Material	Gold
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Contact Mating Area Plating Material Thickness	.76 μ m[30 μ in]
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Contact Type	Pin
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Contact Current Rating (Max)	3.6 A
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Termination Features

Round Termination Post & Tail Diameter	.38 mm[.015 in]
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Termination Post & Tail Length	2.54 mm[.1 in]
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Termination Method to Printed Circuit Board	Through Hole - Solder
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Mechanical Attachment

Mating Retention	With
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PCB Mount Retention Type	Hold-Down Post
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Mating Retention Type	Latching
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Mating Alignment	With
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Mating Alignment Type	Polarization
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PCB Mount Retention	With
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PCB Mount Alignment	Without
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Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	1.27 mm[.05 in]
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Housing Material	LCP
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Dimensions

PCB Thickness (Recommended)	1.57 mm [.062 in]
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Usage Conditions

Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C [-85 – 221 °F]

Operation/Application

Solder Process Feature	Board Standoff
Circuit Application	Signal

Industry Standards

UL Rating	Recognized
Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	23
Packaging Type	Box, Tube

Other

Position Locations Omitted	0
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

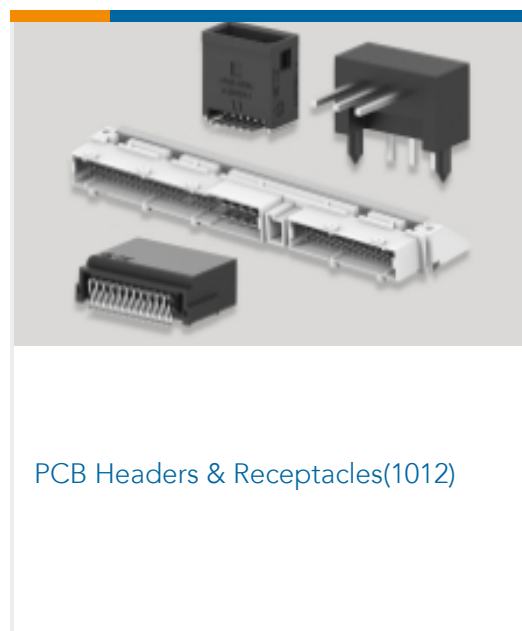
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

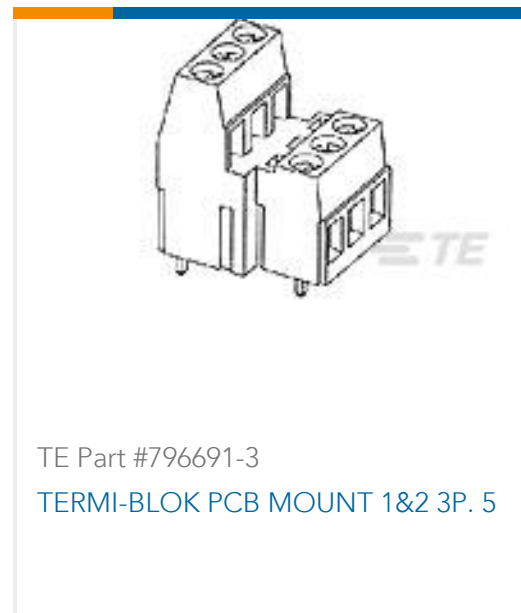


Also in the Series | AMPMODU System 50



Customers Also Bought





Documents

Product Drawings

12 SYSTEM 50 HDR SRRA SHRD SN

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_6-104074-1_W.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-104074-1_W.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-104074-1_W.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Product Specifications

Application Specification

English